

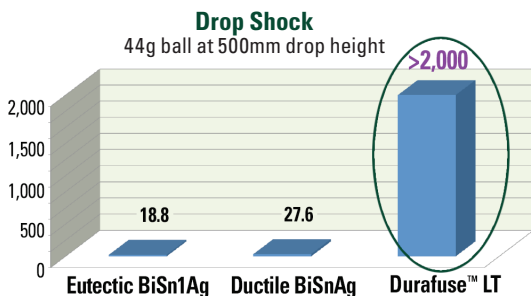
High-Reliability Alloy

Durafuse™ LT*

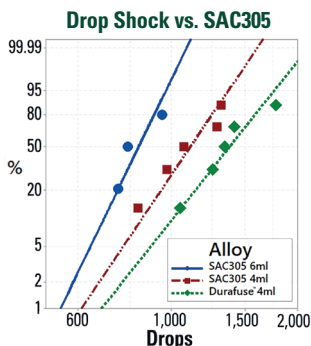
Innovative Low-Temperature Alloy Technology

Durafuse™ LT is a novel mixed alloy system that solves the challenges of brittle bismuth-based, low-temperature solder joints. It provides drop shock resistance two orders of magnitude better than conventional Bi-based alloys and can produce equal or better drop shock performance when compared to SAC305.

Improves Drop Shock Resistance



High-Performance Reliability



- Drop shock resilience
 - Outclasses BiSn or BiSnAg alloys
 - Performance equal to or better than SAC305
- Peak reflow below 210°C
- High re-melt temperature

Weibull plot of 100g ball with 500mm drop height.

*Patented

Contact our engineers: askus@indium.com

Learn more: www.indium.com

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.

Indium Corporation is an ISO 9001:2015 registered company.

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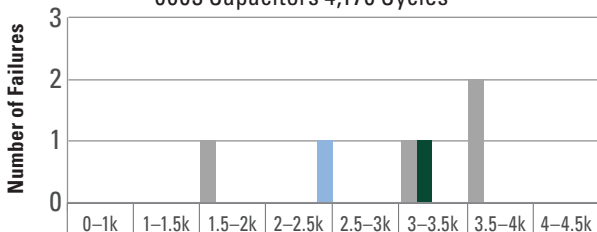
High-Reliability Alloy Indalloy[®] 292

Advanced Reliability for High-Performance Applications

Outstanding Printability, Stability, and Enhanced SIR with Indium8.9HF

Thermal Cycling (-40/150°C)

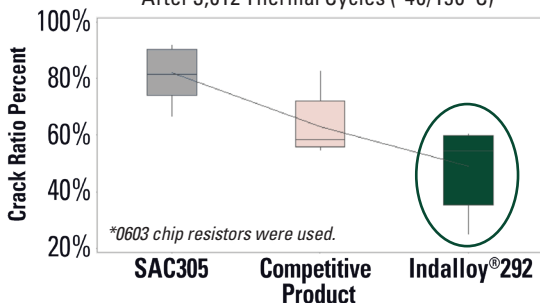
0603 Capacitors 4,170 Cycles



Indalloy[®] 292 has the least amount of failures (1) through 4,170 Cycles.

Solder Joint Crack Comparison*

After 3,012 Thermal Cycles (-40/150°C)



DEFECT:
Cracking

SOLUTION:
Indalloy[®] 292

Excellent thermal cycling performance (-40/150°C). High shear strength and low solder joint cracking. Pinhole elimination improves joint appearance.

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